

40V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on) Max}$	I_D $T_A = +25^\circ C$
40V	27m Ω @ $V_{GS} = 10V$	7.1A
	47m Ω @ $V_{GS} = 4.5V$	5.4A

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

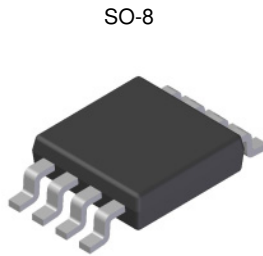
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features and Benefits

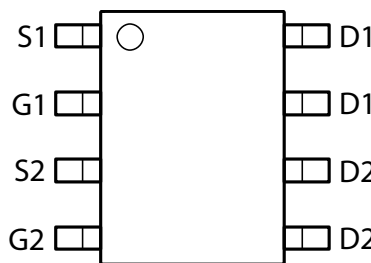
- Low on-resistance
- Fast switching speed
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

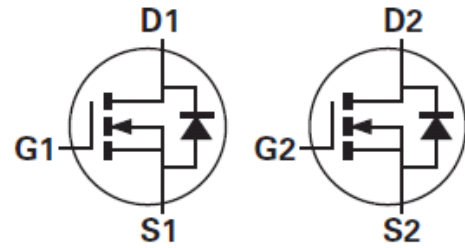
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.074 grams (approximate)



Top View



Top View



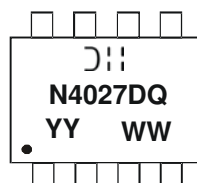
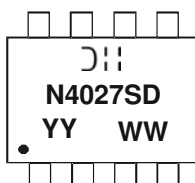
Equivalent Circuit

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMN4027SSD-13	Standard	SO-8	2500 / Tape & Reel
DMN4027SSDQ-13	Automotive	SO-8	2500 / Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



$\text{D} \parallel \parallel$ = Manufacturer's Marking
 N4027SD = Product Type Marking Code for DMN4027SSD-13
 N4027DQ = Product Type Marking Code for DMN4027SSDQ-13
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01-53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

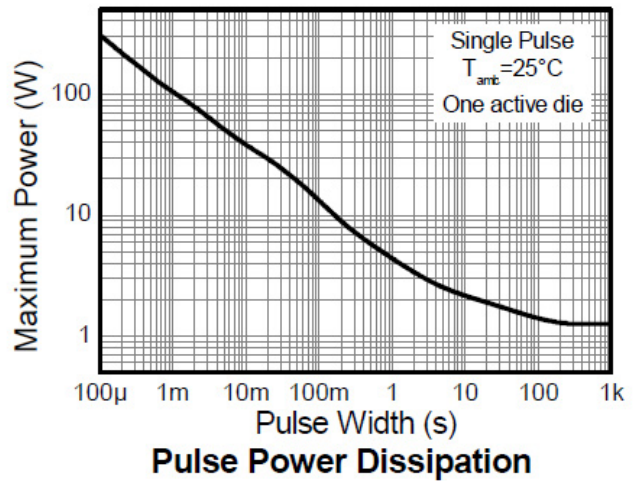
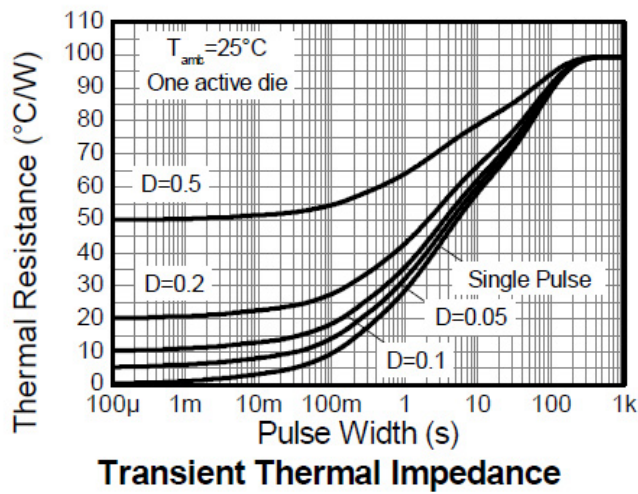
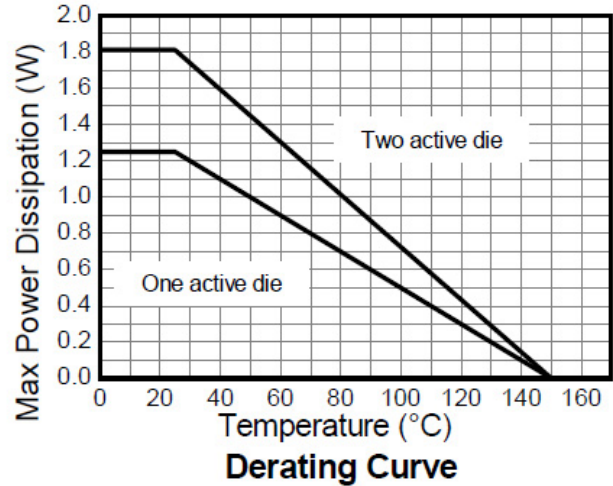
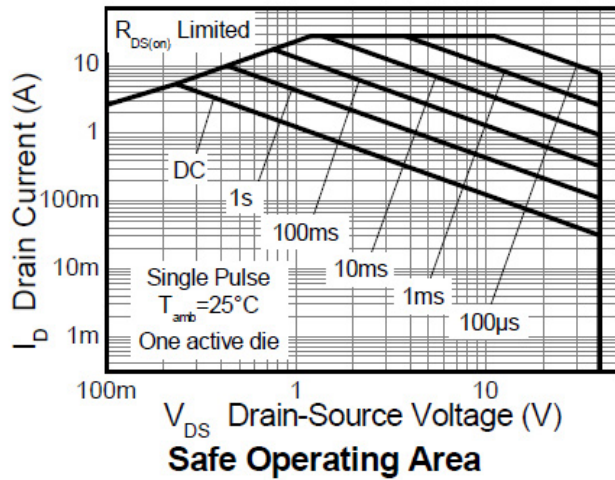
Characteristic		Symbol	Value	Unit	
Drain-Source Voltage		V _{DSS}	40	V	
Gate-Source Voltage (Note 5)		V _{GS}	±20	V	
Continuous Drain Current	V _{GS} = 10V	(Notes 7)	7.1	A	
		T _A = +70°C (Notes 7)	5.7		
		(Notes 6)	5.4		
Pulsed Drain Current	V _{GS} = 10V	(Notes 8)	I _{DM}	28.0	A
Continuous Source Current (Body diode)		(Notes 7)	I _S	3.3	A
Pulsed Source Current (Body diode)		(Notes 8)	I _{SM}	28.0	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Notes 6 & 9)	P _D	1.25 10.0	W mW/°C
	(Notes 6 & 10)		1.8 14.3	
	(Notes 7 & 9)		2.14 17.2	
Thermal Resistance, Junction to Ambient	(Notes 6 & 9)	R _{θJA}	100	°C/W
	(Notes 6 & 10)		70	
	(Notes 7 & 9)		58	
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	R _{θJL}	53	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

- Notes:
5. AEC-Q101 V_{GS} maximum is ±16V.
 6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 7. Same as note (3), except the device is measured at t ≤ 10 sec.
 8. Same as note (3), except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
 9. For a dual device with one active die.
 10. For a device with two active die running at equal power.
 11. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

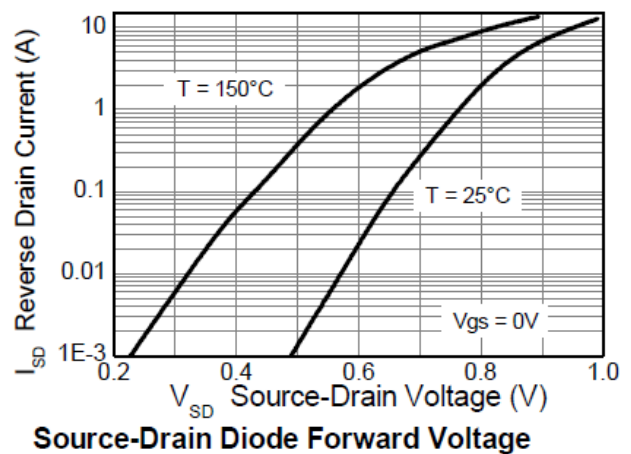
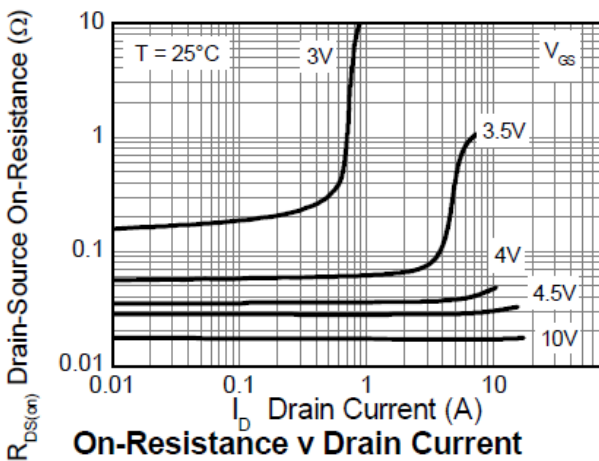
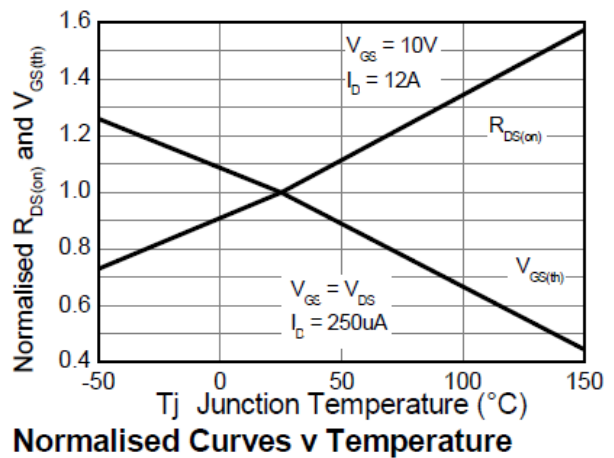
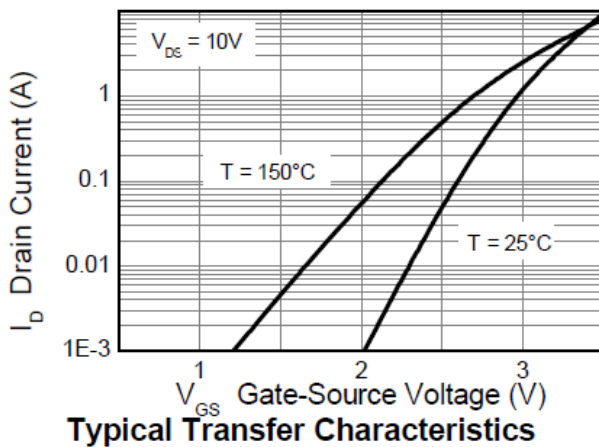
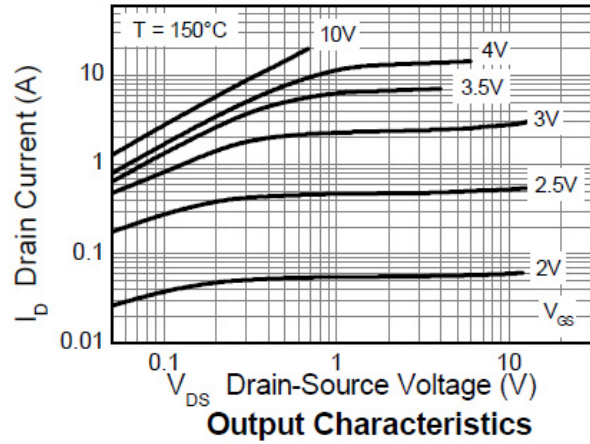
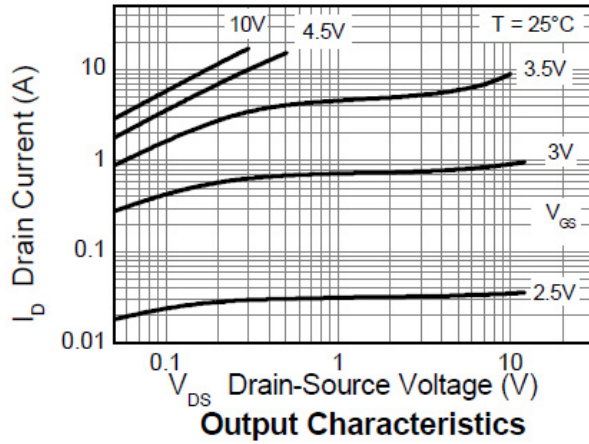


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

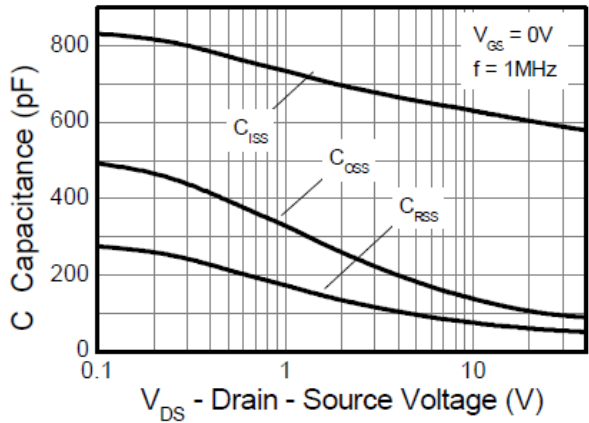
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	40	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 40V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 12)	R _{DS(ON)}	—	0.017	0.027	Ω	V _{GS} = 10V, I _D = 7A
			0.031	0.047		V _{GS} = 4.5V, I _D = 6A
Forward Transconductance (Notes 12 & 13)	g _{fs}	—	22.8	—	S	V _{DS} = 15V, I _D = 7A
Diode Forward Voltage (Note 12)	V _{SD}	—	0.86	1.1	V	I _S = 7A, V _{GS} = 0V
Reverse recovery time (Note 13)	t _{rr}	—	12.1	—	ns	I _S = 2.1A, di/dt = 100A/μs
Reverse recovery charge (Note 13)	Q _{rr}	—	5.1	—	nC	
DYNAMIC CHARACTERISTICS (Note 13)						
Input Capacitance	C _{iSS}	—	604	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oSS}	—	106	—	pF	
Reverse Transfer Capacitance	C _{rSS}	—	59.6	—	pF	
Total Gate Charge (Note 14)	Q _g	—	6.3	—	nC	V _{GS} = 4.5V
Total Gate Charge Note 14)	Q _g	—	12.9	—	nC	V _{GS} = 10V
Gate-Source Charge Note 14)	Q _{gs}	—	2.4	—	nC	
Gate-Drain Charge Note 14)	Q _{gd}	—	3.3	—	nC	
Turn-On Delay Time Note 14)	t _{D(on)}	—	3.1	—	ns	V _{DD} = 20V, V _{GS} = 10V I _D = 1A, R _G ≅ 6.0Ω
Turn-On Rise Time Note 14)	t _r	—	3.1	—	ns	
Turn-Off Delay Time (Note 14)	t _{D(off)}	—	15.4	—	ns	
Turn-Off Fall Time Note 14)	t _f	—	7.5	—	ns	

- Notes: 12. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
13. For design aid only, not subject to production testing.
14. Switching characteristics are independent of operating junction temperatures.

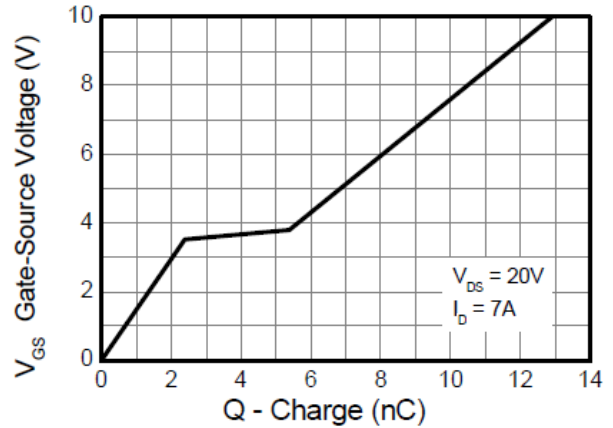
Typical Characteristics



Typical Characteristics (cont.)

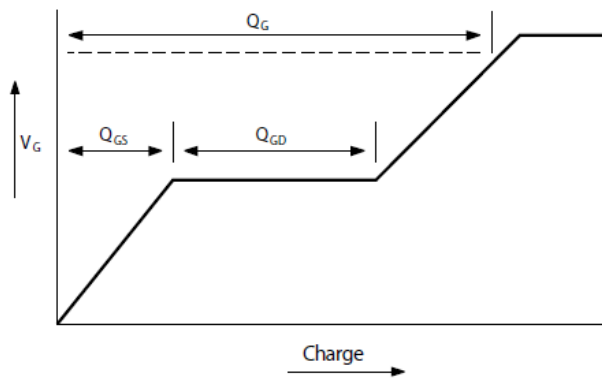


Capacitance v Drain-Source Voltage

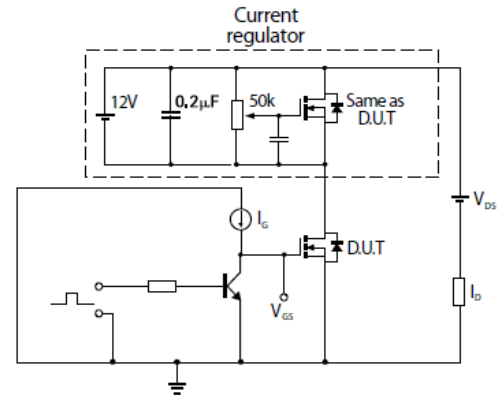


Gate-Source Voltage v Gate Charge

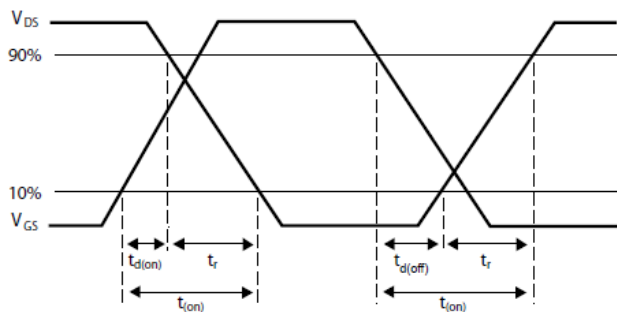
Test Circuits



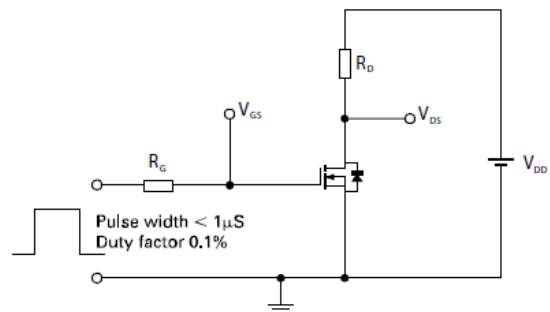
Basic gate charge waveform



Gate charge test circuit



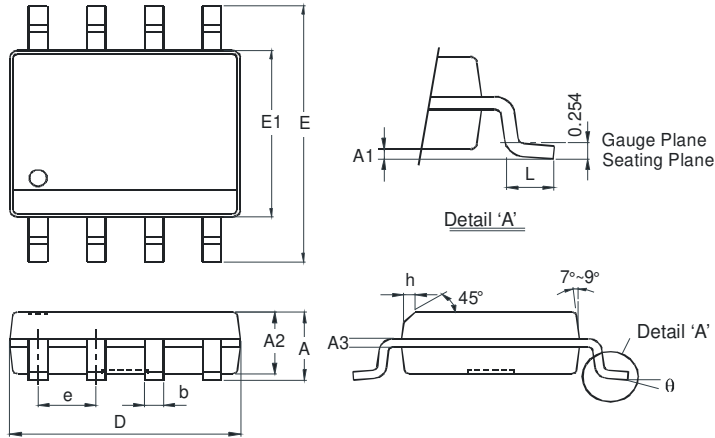
Switching time waveforms



Switching time test circuit

Package Outline Dimensions

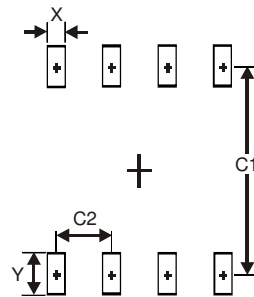
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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